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Applications of "<u>Embedded - Microcontrollers</u>"

Details	
Product Status	Obsolete
Core Processor	MIPS32® M4K™
Core Size	32-Bit Single-Core
Speed	40MHz
Connectivity	I ² C, IrDA, LINbus, PMP, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, I ² S, POR, PWM, WDT
Number of I/O	25
Program Memory Size	16KB (16K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	4K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 3.6V
Data Converters	A/D 12x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	36-VFTLA Exposed Pad
Supplier Device Package	36-VTLA (5x5)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic32mx110f016ct-v-tl

3.0 CPU

Note:

This data sheet summarizes the features of the PIC32MX1XX/2XX 28/36/44-pin Family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 2.** "CPU" (DS60001113), which is available from the *Documentation > Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32). Resources for the MIPS32[®] M4K[®] Processor Core are available at: www.imgtec.com.

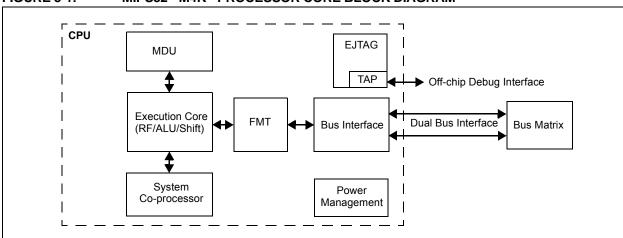
The MIPS32® M4K® Processor Core is the heart of the PIC32MX1XX/2XX family processor. The CPU fetches instructions, decodes each instruction, fetches source operands, executes each instruction and writes the results of instruction execution to the destinations.

3.1 Features

- · 5-stage pipeline
- · 32-bit address and data paths
- MIPS32 Enhanced Architecture (Release 2)
 - Multiply-accumulate and multiply-subtract instructions
 - Targeted multiply instruction
 - Zero/One detect instructions
 - WAIT instruction
 - Conditional move instructions (MOVN, MOVZ)
 - Vectored interrupts
 - Programmable exception vector base
 - Atomic interrupt enable/disable
 - Bit field manipulation instructions

- MIPS16e[®] code compression
 - 16-bit encoding of 32-bit instructions to improve code density
 - Special PC-relative instructions for efficient loading of addresses and constants
 - SAVE and RESTORE macro instructions for setting up and tearing down stack frames within subroutines
 - Improved support for handling 8 and 16-bit data types
- Simple Fixed Mapping Translation (FMT) mechanism
- · Simple dual bus interface
 - Independent 32-bit address and data buses
 - Transactions can be aborted to improve interrupt latency
- · Autonomous multiply/divide unit
 - Maximum issue rate of one 32x16 multiply per clock
 - Maximum issue rate of one 32x32 multiply every other clock
 - Early-in iterative divide. Minimum 11 and maximum 33 clock latency (dividend (rs) sign extension-dependent)
- Power control
 - Minimum frequency: 0 MHz
 - Low-Power mode (triggered by WAIT instruction)
 - Extensive use of local gated clocks
- · EJTAG debug and instruction trace
 - Support for single stepping
 - Virtual instruction and data address/value
 - Breakpoints

FIGURE 3-1: MIPS32® M4K® PROCESSOR CORE BLOCK DIAGRAM



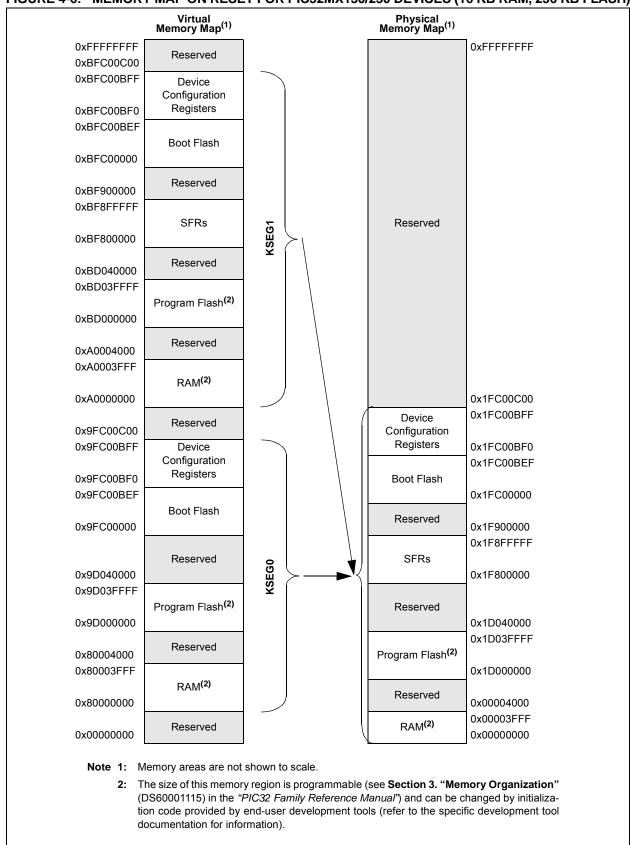


FIGURE 4-6: MEMORY MAP ON RESET FOR PIC32MX130/230 DEVICES (16 KB RAM, 256 KB FLASH)

REGISTER 4-4: BMXDUPBA: DATA RAM USER PROGRAM BASE ADDRESS REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
24.24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
31:24	_	_	-	_			_	_
22.46	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
23:16	_	_	_	_	_	_	_	_
45.0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R-0	R-0
15:8				BMXDU	PBA<15:8>			
7.0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0
7:0				BMXDU	PBA<7:0>			

Legend:

R = Readable bit W = Writable bit U = Unimplemented bit, read as '0'

-n = Value at POR '1' = Bit is set '0' = Bit is cleared x = Bit is unknown

bit 31-16 Unimplemented: Read as '0'

bit 15-10 BMXDUPBA<15:10>: DRM User Program Base Address bits

When non-zero, the value selects the relative base address for User mode program space in RAM, BMXDUPBA must be greater than BMXDUDBA.

bit 9-0 **BMXDUPBA<9:0>:** Read-Only bits

This value is always '0', which forces 1 KB increments

Note 1: At Reset, the value in this register is forced to zero, which causes all of the RAM to be allocated to Kernal mode data usage.

2: The value in this register must be less than or equal to BMXDRMSZ.

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USB Control Registers

TABLE 10-1: USB REGISTER MAP

ess				Bits 9															
Virtual Address (BF88_#)	Register Name ⁽¹⁾	Bit Range	31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	All Resets
5040	U1OTGIR ⁽²⁾	31:16 15:0	_	_		_	_		_	_	— IDIF	— T1MSECIF	- LSTATEIF	— ACTVIF	— SESVDIF	— SESENDIF	_	- VBUSVDIF	0000
5050	U10TGIE	31:16 15:0	_	_	_	_	_	_	_	_	— IDIE	— T1MSECIE	— LSTATEIE	— ACTVIE	— SESVDIE	— SESENDIE	_	— VBUSVDIE	0000
5060	U1OTGSTAT ⁽³⁾	31:16	_	_	_	_			_	_	_		_	_	_	_	_	_	0000
5070		15:0 31:16	_	_		_		_			ID —		LSTATE —		SESVD —	SESEND —	_	VBUSVD —	0000
		15:0 31:16					_			_	DPPULUP —	DMPULUP —	DPPULDWN —	DMPULDWN —	VBUSON —	OTGEN —	VBUSCHG	VBUSDIS —	0000
5080	U1PWRC	15:0	_	_	_	_	_	_	_	_	UACTPND ⁽⁴⁾	_	_	USLPGRD	USBBUSY	_	USUSPEND	USBPWR	0000
5200	U1IR ⁽²⁾	31:16 15:0		_	_	_		_	_	_	STALLIF	— ATTACHIF	RESUMEIF	IDLEIF	TRNIF	SOFIF	UERRIF	URSTIF DETACHIF	0000
		31:16	_	_	-	_	_	_	-	_	_	_	_	_	_	_	_	_	0000
5210	U1IE	15:0	_	_	-	_	-	_	-	_	STALLIE	ATTACHIE	RESUMEIE	IDLEIE	TRNIE	SOFIE	UERRIE	URSTIE DETACHIE	0000
5220	U1EIR ⁽²⁾	31:16	_	_		_	_			_	_	_	_	_	_	_	— CRC5EF	_	0000
5220		15:0	_	_		_	_	_	-	_	BTSEF	BMXEF	DMAEF	BTOEF	DFN8EF	CRC16EF	EOFEF	PIDEF	0000
5230	U1EIE	31:16	_		_	_							_	_	_	_	CRC5EE	_	0000
		15:0	_	_		_	_	_		_	BTSEE	BMXEE	DMAEE	BTOEE	DFN8EE	CRC16EE	EOFEE	PIDEE	0000
5240	U1STAT ⁽³⁾	31:16 15:0	_	_	_	_		_	_	_	_	— ENDF	T<3:0>	_	DIR	PPBI	_	_	0000
		31:16	_	_	_	_		_	_	_	_	_	— DICTRIC	_	_	_	_	_	0000
5250	U1CON	15:0	_	_	_	_	_	_	_	_	JSTATE	SE0	PKTDIS TOKBUSY	USBRST	HOSTEN	RESUME	PPBRST	USBEN SOFEN	0000
5260	U1ADDR	31:16 15:0									— LSPDEN	_	_		— VADDR<6:	<u> </u>	_	_	0000
5270	U1BDTP1	31:16	_	_		_				_	—	_	_	_	_	_	_	_	0000
,	··	15:0	— D	_	_	_	<u> </u>		_				BD	TPTRL<15:9	•			_	0000

x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

With the exception of those noted, all registers in this table (except as noted) have corresponding CLR, SET and INV registers at their virtual address, plus an offset of 0x4, 0x8, and 0xC respectively. See Section 11.2 "CLR, SET and INV Registers" for more information.

^{2:} This register does not have associated SET and INV registers.

This register does not have associated CLR, SET and INV registers.

Reset value for this bit is undefined.

REGISTER 10-10: U1STAT: USB STATUS REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
31.24	-	_	-	-	-	-	-	_
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
23.10	-	_	-	-	-	-	-	_
15:8	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
15.6	-	_	-	-	-	-	-	_
7:0	R-x	R-x	R-x	R-x	R-x	R-x	U-0	U-0
7.0		ENDP [*]	T<3:0>		DIR	PPBI	_	_

Legend:

R = Readable bit W = Writable bit U = Unimplemented bit, read as '0'

-n = Value at POR '1' = Bit is set '0' = Bit is cleared x = Bit is unknown

bit 31-8 Unimplemented: Read as '0'

bit 7-4 ENDPT<3:0>: Encoded Number of Last Endpoint Activity bits

(Represents the number of the Buffer Descriptor Table, updated by the last USB transfer.)

1111 = Endpoint 15

1110 = Endpoint 14

:

.

0001 = Endpoint 1

0000 = Endpoint 0

- bit 3 DIR: Last Buffer Descriptor Direction Indicator bit
 - 1 = Last transaction was a transmit (TX) transfer
 - 0 = Last transaction was a receive (RX) transfer
- bit 2 **PPBI:** Ping-Pong Buffer Descriptor Pointer Indicator bit
 - 1 = The last transaction was to the ODD Buffer Descriptor bank
 - 0 = The last transaction was to the EVEN Buffer Descriptor bank
- bit 1-0 Unimplemented: Read as '0'

Note: The U1STAT register is a window into a 4-byte FIFO maintained by the USB module. U1STAT value is only valid when the TRNIF (U1IR<3>) bit is active. Clearing the TRNIF bit advances the FIFO. Data in register is invalid when the TRNIF bit = 0.

11.1 Parallel I/O (PIO) Ports

All port pins have 10 registers directly associated with their operation as digital I/O. The data direction register (TRISx) determines whether the pin is an input or an output. If the data direction bit is a '1', then the pin is an input. All port pins are defined as inputs after a Reset. Reads from the latch (LATx) read the latch. Writes to the latch write the latch. Reads from the port (PORTx) read the port pins, while writes to the port pins write the latch.

11.1.1 OPEN-DRAIN CONFIGURATION

In addition to the PORTx, LATx, and TRISx registers for data control, some port pins can also be individually configured for either digital or open-drain output. This is controlled by the Open-Drain Control register, ODCx, associated with each port. Setting any of the bits configures the corresponding pin to act as an open-drain output.

The open-drain feature allows the generation of outputs higher than VDD (e.g., 5V) on any desired 5V-tolerant pins by using external pull-up resistors. The maximum open-drain voltage allowed is the same as the maximum VIH specification.

See the "Pin Diagrams" section for the available pins and their functionality.

11.1.2 CONFIGURING ANALOG AND DIGITAL PORT PINS

The ANSELx register controls the operation of the analog port pins. The port pins that are to function as analog inputs must have their corresponding ANSEL and TRIS bits set. In order to use port pins for I/O functionality with digital modules, such as Timers, UARTs, etc., the corresponding ANSELx bit must be cleared.

The ANSELx register has a default value of 0xFFFF; therefore, all pins that share analog functions are analog (not digital) by default.

If the TRIS bit is cleared (output) while the ANSELx bit is set, the digital output level (VOH or VOL) is converted by an analog peripheral, such as the ADC module or Comparator module.

When the PORT register is read, all pins configured as analog input channels are read as cleared (a low level).

Pins configured as digital inputs do not convert an analog input. Analog levels on any pin defined as a digital input (including the ANx pins) can cause the input buffer to consume current that exceeds the device specifications.

11.1.3 I/O PORT WRITE/READ TIMING

One instruction cycle is required between a port direction change or port write operation and a read operation of the same port. Typically this instruction would be a NOP.

11.1.4 INPUT CHANGE NOTIFICATION

The input change notification function of the I/O ports allows the PIC32MX1XX/2XX 28/36/44-pin Family devices to generate interrupt requests to the processor in response to a change-of-state on selected input pins. This feature can detect input change-of-states even in Sleep mode, when the clocks are disabled. Every I/O port pin can be selected (enabled) for generating an interrupt request on a change-of-state.

Five control registers are associated with the CN functionality of each I/O port. The CNENx registers contain the CN interrupt enable control bits for each of the input pins. Setting any of these bits enables a CN interrupt for the corresponding pins.

The CNSTATx register indicates whether a change occurred on the corresponding pin since the last read of the PORTx bit.

Each I/O pin also has a weak pull-up and a weak pull-down connected to it. The pull-ups act as a current source or sink source connected to the pin, and eliminate the need for external resistors when push-button or keypad devices are connected. The pull-ups and pull-downs are enabled separately using the CNPUx and the CNPDx registers, which contain the control bits for each of the pins. Setting any of the control bits enables the weak pull-ups and/or pull-downs for the corresponding pins.

Note: Pull-ups and pull-downs on change notification pins should always be disabled when the port pin is configured as a digital output.

An additional control register (CNCONx) is shown in Register 11-3.

11.2 CLR, SET and INV Registers

Every I/O module register has a corresponding CLR (clear), SET (set) and INV (invert) register designed to provide fast atomic bit manipulations. As the name of the register implies, a value written to a SET, CLR or INV register effectively performs the implied operation, but only on the corresponding base register and only bits specified as '1' are modified. Bits specified as '0' are not modified.

Reading SET, CLR and INV registers returns undefined values. To see the affects of a write operation to a SET, CLR, or INV register, the base register must be read.

TABLE 11-6: PERIPHERAL PIN SELECT INPUT REGISTER MAP

SS										В	its								
Virtual Address (BF80_#)	Register Name	Bit Range	31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	All Resets
FA04	INT1R	31:16	_	_	_	_	_	_	_	_	_	_	_	_	_	_	_	_	0000
FAU4	INTIK	15:0	_	_	_	_	_	_		_	_	_		_		INT1F	R<3:0>		0000
FA08	INT2R	31:16	_	_	_	_	_	_	_	_	_	_	_	_	_	_	_	_	0000
17100	IIVIZIX	15:0	_	_	_	_	_	_	_	_	_	_	_	_		INT2F	R<3:0>		0000
FA0C	INT3R	31:16	_	_	_	_	_	_	_	_	_	_	_	_	_	_	_	_	0000
17.00	IIIII	15:0	_	_	_	_	_	_	_	_	_	_	_	_		INT3F	R<3:0>		0000
FA10	INT4R	31:16			_	_	_					_			_	_	_	_	0000
.,		15:0				_						_				INT4F	R<3:0>	ı	0000
FA18	T2CKR	31:16	_	_	_	_	_	_	_	_	_	_	_	_	_	_	_	_	0000
		15:0	_	_	_	_	_	_	_	_	_	_	_	_		T2CKI	R<3:0>		0000
FA1C	T3CKR	31:16	_	_	_	_	_	_	_	_	_	_	_	_	_	_	_	_	0000
		15:0			_	_	_	_				_				T3CKI	R<3:0>	ı	0000
FA20	T4CKR	31:16	_	_	_	_	_	_	_	_	_	_	_	_	_	_	_	_	0000
		15:0	_	_	_	_	_	_	_	_	_	_	_	_		T4CKI	R<3:0>		0000
FA24	T5CKR	31:16			_		_			_		_		_	_	_	_	_	0000
		15:0	_	_	_			_		_	_	_	_	_		T5CKI	R<3:0>		0000
FA28	IC1R	31:16	_	_	_			_		_	_	_	_	_	_	_	_	_	0000
	_	15:0	_	_	_			_		_	_	_	_	_		IC1R	<3:0>		0000
FA2C	IC2R	31:16	_	_	_			_		_	_	_	_	_	_	_	_	_	0000
	_	15:0	_	_	_			_		_		_		_		IC2R	<3:0>		0000
FA30	IC3R	31:16	_	_	_			_		_		_		_	_	_	_	_	0000
		15:0		_				_		_		_		_		IC3R	<3:0>		0000
FA34	IC4R	31:16																_	0000
		15:0														IC4R	<3:0>		0000
FA38	IC5R	31:16		_				_		_		_		_	_	_		_	0000
		15:0	_	_				_		_		_		_		IC5R	<3:0>		0000
FA48	OCFAR	31:16	_	_	_	_	_	_		_	_	_		_	_	_		_	0000
		15:0	_	_	_	_	_	_		_	_	_		_		OCFA	R<3:0>		0000
FA4C	OCFBR	31:16		_	_	_	_	_				_			_	_		_	0000
		15:0	_	_	_	_	_	_	_	_	_	_	_	_		OCFB	R<3:0>		0000
FA50	U1RXR	31:16	_	_	_	_	_	_	_	_	_	_	_	_	_	_	_	_	0000
	•	15:0	_	_	_	_	_	_	_	_	_	_	_	_		U1RX	R<3:0>		0000

TABLE 11-7: PERIPHERAL PIN SELECT OUTPUT REGISTER MAP (CONTINUED)

ss										В	its								
Virtual Address (BF80_#)	Register Name	Bit Range	31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	All Resets
ED00	RPC8R ⁽¹⁾	31:16	_	_	_	_	_	_	_	_	_	_	_	_	_	_	_	_	0000
FB8C	RPC8R**	15:0	_	_	_	_	_	_	_	_	_	_	_	_		RPC8	<3:0>		0000
ED00	RPC9R ⁽³⁾	31:16	_	_	_	-	_	_	_	_	_	_	_	_	_	_	_	_	0000
FB90	RPC9R ^(*)	15:0	_	_	_		1	1	_	_	_	_	_	_		RPC9	<3:0>		0000

x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1:

This register is only available on 44-pin devices. This register is only available on PIC32MX1XX devices. 2:

This register is only available on 36-pin and 44-pin devices.

14.0 WATCHDOG TIMER (WDT)

Note:

This data sheet summarizes the features of the PIC32MX1XX/2XX 28/36/44-pin Family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 9. "Watchdog, Deadman, and Power-up Timers"** (DS60001114), which are available from the *Documentation > Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32).

The WDT, when enabled, operates from the internal Low-Power Oscillator (LPRC) clock source and can be used to detect system software malfunctions by resetting the device if the WDT is not cleared periodically in software. Various WDT time-out periods can be selected using the WDT postscaler. The WDT can also be used to wake the device from Sleep or Idle mode.

The following are some of the key features of the WDT module:

- · Configuration or software controlled
- · User-configurable time-out period
- · Can wake the device from Sleep or Idle mode

Figure 14-1 illustrates a block diagram of the WDT and Power-up timer.

FIGURE 14-1: WATCHDOG TIMER AND POWER-UP TIMER BLOCK DIAGRAM

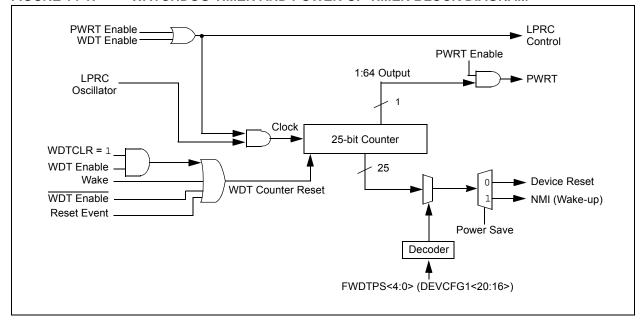


TABLE 22-1: ADC REGISTER MAP (CONTINUED)

ess		ө								Ві	ts								v
Virtual Address (BF80_#)	Register Name	Bit Rang	31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	All Reset
9120	ADC1BUFB	31:16							ADC Res	ult Word B	(ADC1BUF	B<31·0>)							0000
0120	715015015	15:0							7.50 1.00	ait Word B	(7.001001	D 1011.01)							0000
0130	ADC1BUFC	31:16							ADC Bos	ult Word C	(ADC1BUF	C<31:0>)							0000
9130	ADCIBULC	15:0							ADC Res	uit vvoiu C	(ADC IBUF	U<31.02)							0000
0140	ADC1BUFD	31:16							ADC Boo	ult Word D	(ADC1BUF	D-21:0>)							0000
9140	ADCIBULD	15:0							ADC Res	uit vvoiu D	(ADC IBUF	D<31.02)							0000
0150	ADC1BUFE	31:16							ADC Pos	ult Word E	(ADC1BUF	E_31:0\)							0000
9130	ADCIBULE	15:0							ADO RES	uit vvolu E	(ADC IBUE	L~31.0/)							0000
0160	ADC1BUFF	31:16							ADC Box	ult Mord E	(ADC1BLIE	E-21:0~\							0000
9100	ADCIBUFF	15:0							ADC Res	uit vvoid F	(ADC1BUF	F\31.02)							0000

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: This register has corresponding CLR, SET and INV registers at its virtual address, plus offsets of 0x4, 0x8 and 0xC, respectively. See Section 11.2 "CLR, SET and INV Registers" for details.

REGISTER 27-1: DEVCFG0: DEVICE CONFIGURATION WORD 0 (CONTINUED)

bit 18-10 PWP<8:0>: Program Flash Write-Protect bits(3)

```
Prevents selected program Flash memory pages from being modified during code execution.
         111111111 = Disabled
         111111110 = Memory below 0x0400 address is write-protected
         111111101 = Memory below 0x0800 address is write-protected
         111111100 = Memory below 0x0C00 address is write-protected
         111111011 = Memory below 0x1000 (4K) address is write-protected
         111111010 = Memory below 0x1400 address is write-protected
         111111001 = Memory below 0x1800 address is write-protected
         111111000 = Memory below 0x1C00 address is write-protected
         111110111 = Memory below 0x2000 (8K) address is write-protected
         111110110 = Memory below 0x2400 address is write-protected
         111110101 = Memory below 0x2800 address is write-protected
         111110100 = Memory below 0x2C00 address is write-protected
         111110011 = Memory below 0x3000 address is write-protected
         111110010 = Memory below 0x3400 address is write-protected
         111110001 = Memory below 0x3800 address is write-protected
         111110000 = Memory below 0x3C00 address is write-protected
         111101111 = Memory below 0x4000 (16K) address is write-protected
         110111111 = Memory below 0x10000 (64K) address is write-protected
         101111111 = Memory below 0x20000 (128K) address is write-protected
         011111111 = Memory below 0x40000 (256K) address is write-protected
         000000000 = All possible memory is write-protected
         Reserved: Write '1'
         ICESEL<1:0>: In-Circuit Emulator/Debugger Communication Channel Select bits(2)
         11 = PGEC1/PGED1 pair is used
         10 = PGEC2/PGED2 pair is used
         01 = PGEC3/PGED3 pair is used
         00 = PGEC4/PGED4 pair is used<sup>(2)</sup>
         JTAGEN: JTAG Enable bit(1)
         1 = JTAG is enabled
         0 = JTAG is disabled
         DEBUG<1:0>: Background Debugger Enable bits (forced to '11' if code-protect is enabled)
         1x = Debugger is disabled
         0x = Debugger is enabled
Note 1: This bit sets the value for the JTAGEN bit in the CFGCON register.
     2: The PGEC4/PGED4 pin pair is not available on all devices. Refer to the "Pin Diagrams" section for
```

- - availability.
 - 3: The PWP<8:7> bits are only available on devices with 256 KB Flash.

bit 9-5

bit 4-3

bit 2

bit 1-0

SP60 ✓→ SSx **SCKx** (CKP = 0)sėtz SP73 SCKx (CKP = 1)MSb Bit 14 -LSb SDOx SP30,SP31 SP51 SDIx MSb In Bit 14 LSb In SP40

FIGURE 30-13: SPIX MODULE SLAVE MODE (CKE = 1) TIMING CHARACTERISTICS

TABLE 30-31: SPIx MODULE SLAVE MODE (CKE = 1) TIMING REQUIREMENTS

AC CHA	ARACTERIS	псѕ	Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \le \text{TA} \le +85^{\circ}\text{C}$ for Industrial $-40^{\circ}\text{C} \le \text{TA} \le +105^{\circ}\text{C}$ for V-temp							
Param. No.	Symbol	Characteristics ⁽¹⁾	Min.	Typical ⁽²⁾	Max.	Units	Conditions			
SP70	TscL	SCKx Input Low Time (Note 3)	Tsck/2	_	_	ns	_			
SP71	TscH	SCKx Input High Time (Note 3)	Tsck/2	_	_	ns	_			
SP72	TscF	SCKx Input Fall Time	_	5	10	ns	_			
SP73	TscR	SCKx Input Rise Time	_	5	10	ns	_			
SP30	TDOF	SDOx Data Output Fall Time (Note 4)	_		_	ns	See parameter DO32			
SP31	TDOR	SDOx Data Output Rise Time (Note 4)	_	_	_	ns	See parameter DO31			
SP35	TscH2DoV,	SDOx Data Output Valid after	_	_	20	ns	VDD > 2.7V			
	TscL2DoV	SCKx Edge	_	_	30	ns	VDD < 2.7V			
SP40	TDIV2scH, TDIV2scL	Setup Time of SDIx Data Input to SCKx Edge	10	_	_	ns	_			
SP41	TscH2DIL, TscL2DIL	Hold Time of SDIx Data Input to SCKx Edge	10	_	_	ns	_			
SP50	TssL2scH, TssL2scL	SSx ↓ to SCKx ↓ or SCKx ↑ Input	175	_	_	ns	_			

- Note 1: These parameters are characterized, but not tested in manufacturing.
 - Data in "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.
 - 3: The minimum clock period for SCKx is 50 ns.
 - Assumes 50 pF load on all SPIx pins.

FIGURE 30-14: I2Cx BUS START/STOP BITS TIMING CHARACTERISTICS (MASTER MODE)

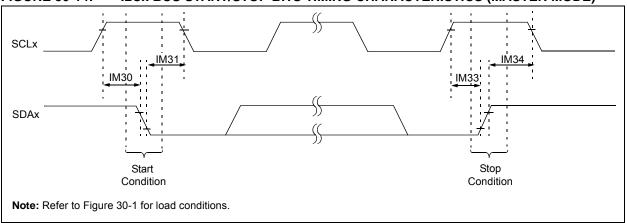


FIGURE 30-15: I2Cx BUS DATA TIMING CHARACTERISTICS (MASTER MODE)

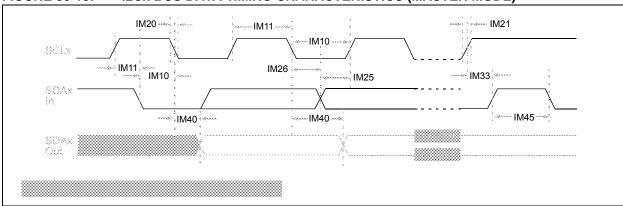
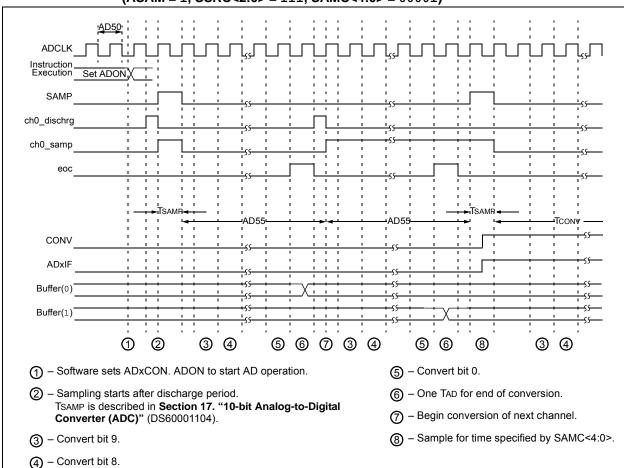


TABLE 30-33: I2Cx BUS DATA TIMING REQUIREMENTS (SLAVE MODE) (CONTINUED)

AC CHA	RACTERIS	STICS		(unless other	rwise st	ated) re -40°	ons: 2.3V to 3.6V $C \le TA \le +85^{\circ}C$ for Industrial $C \le TA \le +105^{\circ}C$ for V-temp
Param. No.	Symbol	Characte	eristics	Min.	Max.	Units	Conditions
IS34	THD:STO	Stop Condition	100 kHz mode	4000	_	ns	_
		Hold Time	400 kHz mode	600	_	ns	
			1 MHz mode (Note 1)	250		ns	
IS40	TAA:SCL	Output Valid from	100 kHz mode	0	3500	ns	_
		Clock	400 kHz mode	0	1000	ns	
			1 MHz mode (Note 1)	0	350	ns	
IS45	TBF:SDA	Bus Free Time	100 kHz mode	4.7	_	μS	The amount of time the bus
			400 kHz mode	1.3		μS	must be free before a new
			1 MHz mode (Note 1)	0.5	_	μS	transmission can start
IS50	Св	Bus Capacitive Loa	ading	_	400	pF	_

Note 1: Maximum pin capacitance = 10 pF for all I2Cx pins (for 1 MHz mode only).

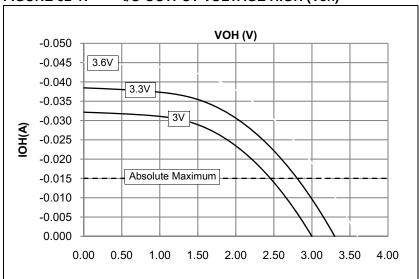
FIGURE 30-19: ANALOG-TO-DIGITAL CONVERSION (10-BIT MODE) TIMING CHARACTERISTICS (ASAM = 1, SSRC<2:0> = 111, SAMC<4:0> = 00001)



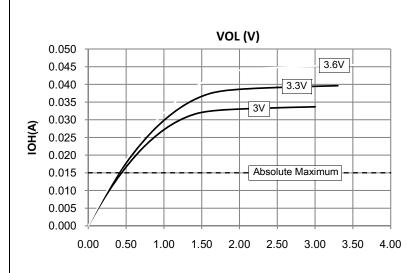
32.0 DC AND AC DEVICE CHARACTERISTICS GRAPHS

Note: The graphs provided following this note are a statistical summary based on a limited number of samples and are provided for design guidance purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore, outside the warranted range.

FIGURE 32-1: I/O OUTPUT VOLTAGE HIGH (VOH)





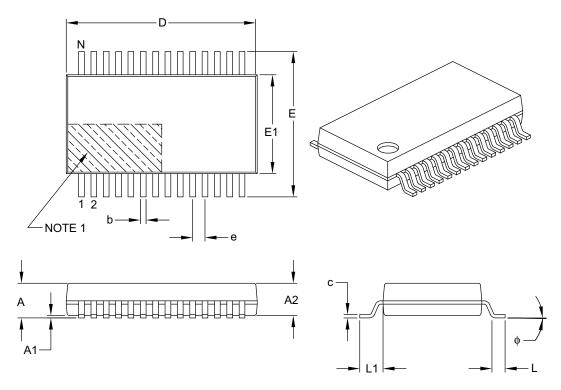


33.2 Package Details

This section provides the technical details of the packages.

28-Lead Plastic Shrink Small Outline (SS) – 5.30 mm Body [SSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	Units		MILLIMETERS	3
Dimens	ion Limits	MIN	NOM	MAX
Number of Pins	N		28	
Pitch	е		0.65 BSC	
Overall Height	Α	_	_	2.00
Molded Package Thickness	A2	1.65	1.75	1.85
Standoff	A1	0.05	_	_
Overall Width	Е	7.40	7.80	8.20
Molded Package Width	E1	5.00	5.30	5.60
Overall Length	D	9.90	10.20	10.50
Foot Length	L	0.55	0.75	0.95
Footprint	L1		1.25 REF	
Lead Thickness	С	0.09	_	0.25
Foot Angle	ф	0°	4°	8°
Lead Width	b	0.22	_	0.38

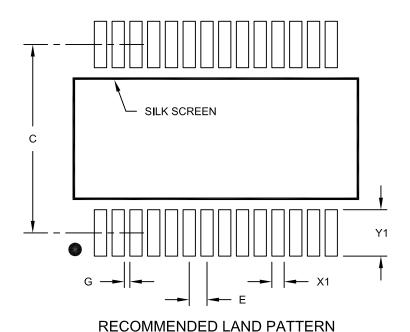
Notes:

- 1. Pin 1 visual index feature may vary, but must be located within the hatched area.
- 2. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.20 mm per side.
- 3. Dimensioning and tolerancing per ASME Y14.5M.
 - BSC: Basic Dimension. Theoretically exact value shown without tolerances.
 - REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-073B

28-Lead Plastic Shrink Small Outline (SS) - 5.30 mm Body [SSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units MILLIMETERS **Dimension Limits** MIN MOM MAX Contact Pitch 0.65 BSC Ε Contact Pad Spacing С 7.20 Contact Pad Width (X28) X1 0.45 <u>Y1</u> Contact Pad Length (X28) 1.75 G 0.20 Distance Between Pads

Notes:

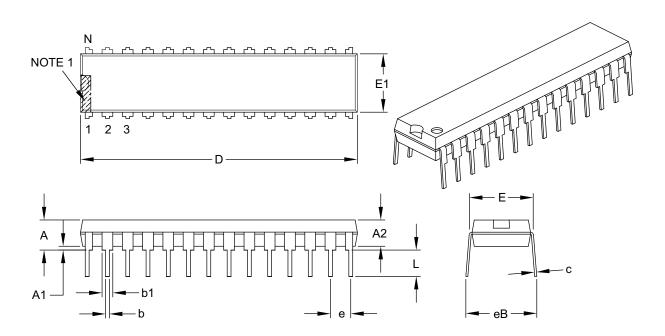
1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2073A

28-Lead Skinny Plastic Dual In-Line (SP) – 300 mil Body [SPDIP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	Units		INCHES	
	Dimension Limits	MIN	NOM	MAX
Number of Pins	N		28	
Pitch	е		.100 BSC	
Top to Seating Plane	A	-	_	.200
Molded Package Thickness	A2	.120	.135	.150
Base to Seating Plane	A1	.015	_	-
Shoulder to Shoulder Width	E	.290	.310	.335
Molded Package Width	E1	.240	.285	.295
Overall Length	D	1.345	1.365	1.400
Tip to Seating Plane	L	.110	.130	.150
Lead Thickness	С	.008	.010	.015
Upper Lead Width	b1	.040	.050	.070
Lower Lead Width	b	.014	.018	.022
Overall Row Spacing §	еВ	-	_	.430

Notes:

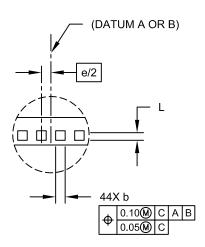
- 1. Pin 1 visual index feature may vary, but must be located within the hatched area.
- 2. § Significant Characteristic.
- 3. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" per side.
- 4. Dimensioning and tolerancing per ASME Y14.5M.

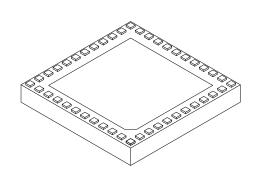
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-070B

44-Terminal Very Thin Leadless Array Package (TL) – 6x6x0.9 mm Body With Exposed Pad [VTLA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging





DETAIL A

	Units	N	ILLIMETER	S
Dimension	Limits	MIN	NOM	MAX
Number of Pins	Ν		44	
Number of Pins per Side	ND		12	
Number of Pins per Side	NE		10	
Pitch	е		0.50 BSC	
Overall Height	Α	0.80	0.90	1.00
Standoff	A1	0.025	-	0.075
Overall Width	Е		6.00 BSC	
Exposed Pad Width	E2	4.40	4.55	4.70
Overall Length	D		6.00 BSC	
Exposed Pad Length	D2	4.40	4.55	4.70
Contact Width	b	0.20	0.25	0.30
Contact Length	L	0.20	0.25	0.30
Contact-to-Exposed Pad	K	0.20	-	-

Notes:

- 1. Pin 1 visual index feature may vary, but must be located within the hatched area.
- 2. Package is saw singulated.
- 3. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-157C Sheet 2 of 2